

<b>Notice of References Cited</b>		Application/Control No.	Applicant(s)/Patent Under Reexamination MIKAMI ET AL.	
		Examiner Christian Wilson	Art Unit 2891	Page 1 of 1

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	U	Ramanath et al., Self-assembled subnanolayers as interfacial adhesion enhancers and diffusion barriers for integrated circuits, <i>Appl. Phys. Lett.</i> , 83 (July 2003) 383.
	V	Semaltianos et al., Copper chemical vapour deposition on organosilane-treated SiO <sub>2</sub> surfaces, <i>Appl. Surf. Sci.</i> , 222 (2004) 102.
	W	Doppelt et al., High affinity self-assembled monolayers for copper CVD, <i>Microelectronic Engineering</i> , 76 (2004) 113.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.